

Features

60Watts peak pulse power ($t_p = 8/20\mu s$)
Unidirectional configurations
Solid-state silicon-avalanche technology
Low clamping voltage
Low leakage current
Low capacitance ($C_j = 0.2pF$ typ. I/O to I/O)
IEC 61000-4-2 $\pm 20kV$ contact $\pm 25kV$ air
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 4.5A (8/20 μs)

Mechanical Data

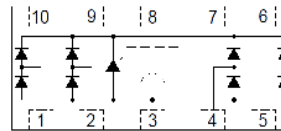
Tiny DFN10L(2.5mmx1.0mm) package
Molding compound flammability rating: UL 94V-0
Packaging: Tape and Reel
RoHS/WEEE Compliant

Applications

USB3.0, USB2.0, Ethernet
HDMI 2.0, Displayport 1.3, eSATA
Unified Display interface
Digital Visual Interface
High speed serial interface

.117KL

Schematic & PIN Configuration



DFN2510



Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	60	Watts
Peak Pulse Current ($t_p = 8/20\mu s$) (note1)	I_{PP}	4.5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	25 20	kV
Lead Soldering Temperature	T_L	260(10seconds)	$^{\circ}C$
Junction Temperature	T_J	-55 to + 125	$^{\circ}C$
Storage Temperature	T_{stg}	-55 to + 125	$^{\circ}C$

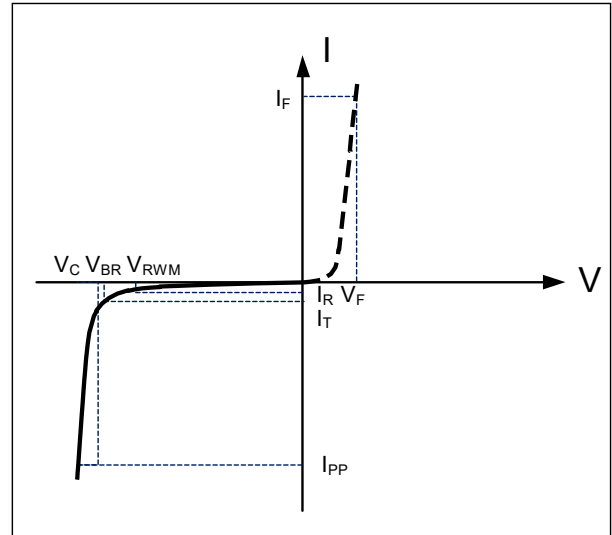
Electrical Characteristics (TA=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				5.0	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	6.0			V
Reverse Leakage Current	I_R	$V_{RWM}=5V, T=25^\circ C$			100	μA
Peak Pulse Current	I_{PP}	$t_p = 8/20\mu s$			4.5	A
Clamping Voltage	V_C	$I_{PP}=4A, t_p=8/20\mu s$		13		V
Clamping Voltage	V_{CL}	$I_{PP} = 16 A; t_p = TLP$		22		V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$ I/O to I/O		0.2		pF
		$V_R = 0V, f = 1MHz$ I/O to GND		0.4		

Electrical Parameters (TA = 25°C unless otherwise noted)

	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

Note: .8/20 μs pulse waveform.



RATING AND CHARACTERISTIC CURVES

Fig.1 Peak Pulse Power Rating Curve

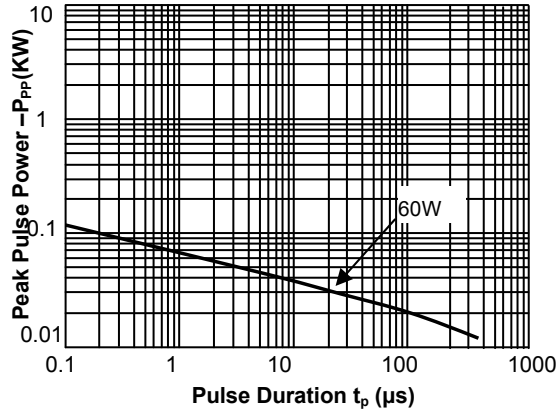


Fig.2 Pulse Derating Curve

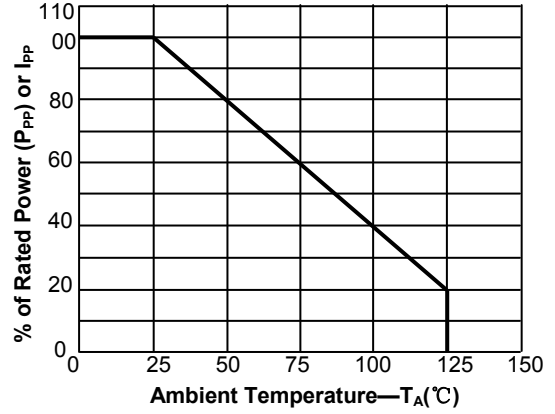


Fig.3 Pulse Waveform-8/20 μs

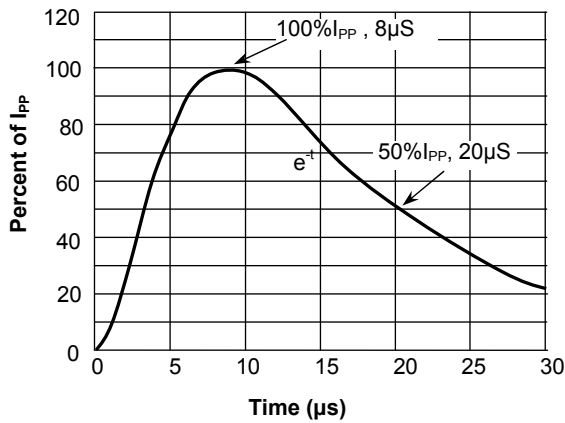


Fig.4 Pulse Waveform-ESD(IEC61000-4-2)

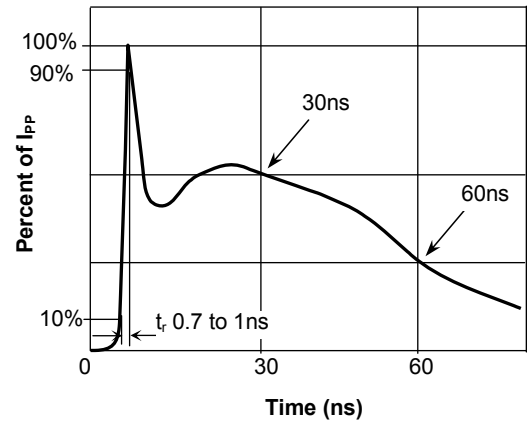


Figure5: Positive Clamping voltage (TLP)

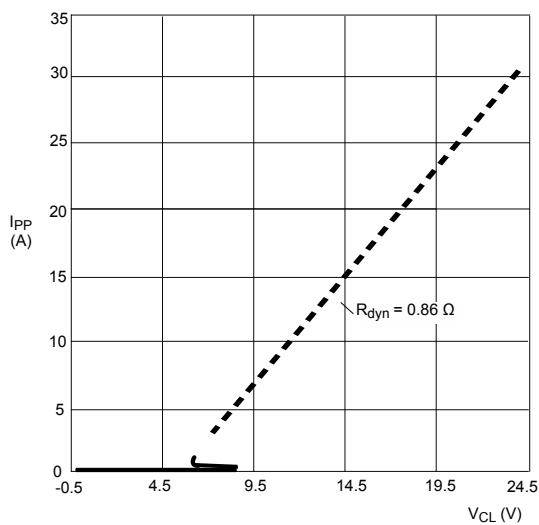
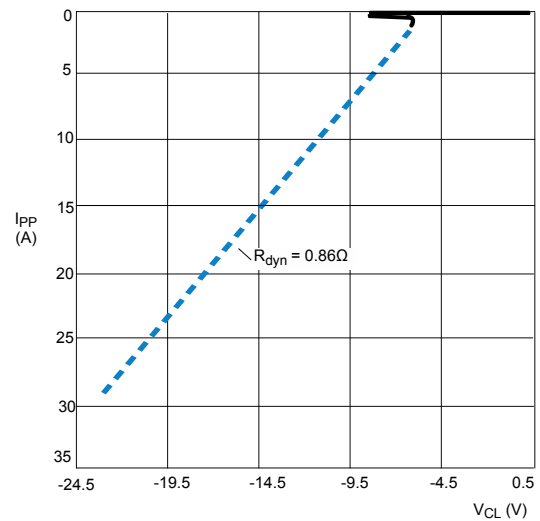
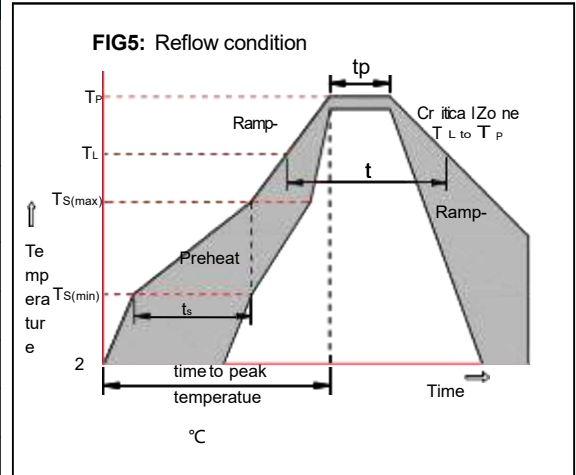


Figure6: Negative Clamping voltage (TLP)



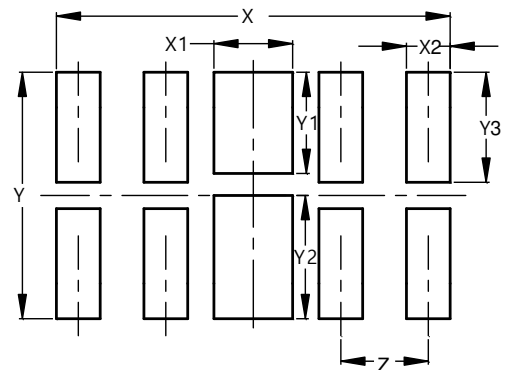
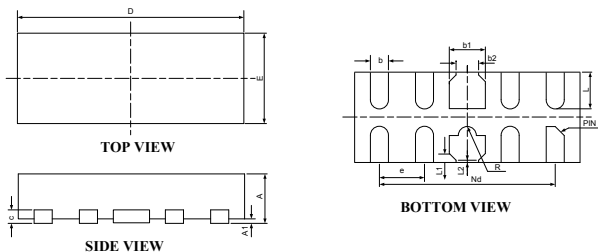
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

DFN2510-10L

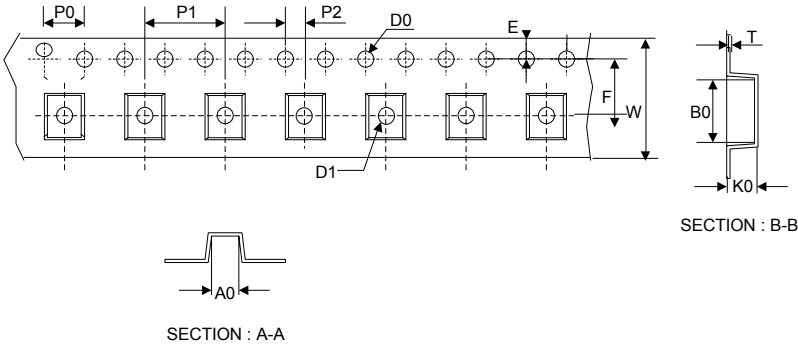
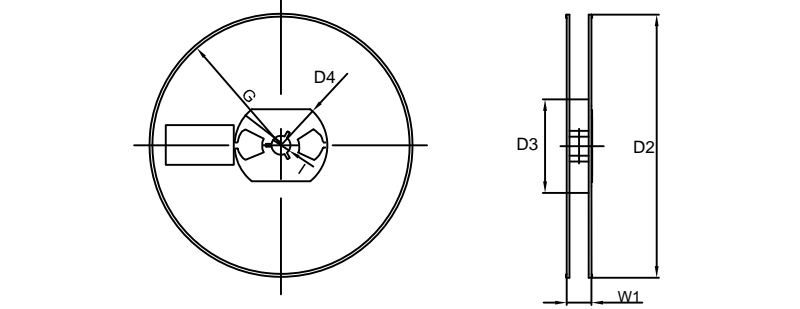


SYM	DIMENSIONS					
	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
b2	0.20	0.25	0.30	0.008	0.010	0.012
c	0.10	0.15	0.20	0.004	0.006	0.008
D	2.45	2.50	2.55	0.098	0.100	0.102
e	0.50BSC			0.020BSC		
Nd	2.00BSC			0.080BSC		
E	0.95	1.00	1.05	0.038	0.040	0.042
L	0.35	0.40	0.45	0.014	0.016	0.018
L1	0.075REF			0.003REF		
L2	0.050REF			0.002REF		
h	0.08	0.12	0.15	0.003	0.005	0.006
R	0.05	0.10	0.15	0.002	0.004	0.006

Dimensions	Value (in mm)
Z	0.500
X	2.250
X1	0.450
X2	0.250
Y	1.400
Y1	0.570
Y2	0.700
Y3	0.600

Dimensions in inches and (millimeters)

Tape & reel specification

Tape	Symbol	Dimension (mm)
	P0	4.00±0.20
	P1	4.00±0.20
	P2	1.55±0.20
	D0	1.55±0.20
	D1	0.65±0.20
	E	1.55±0.25
	F	3.60±0.20
	W	8.00±0.20
	A0	1.65±0.20
	B0	3.00±0.20
	K0	1.10±0.20
	T	0.20±0.20
	7" Reel	D2
	D3	55Min.
	D4	R24.6±2.0
	G	R82.0±2.0
	I	13.0±2.0
	W1	10.20±3.0
	Quantity: 3000PCS	